

**SEMICONDUCTOR PACKAGE DEVICE AND METHOD OF
FORMATION AND TESTING**

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Abstract of the Disclosure

A package device (10, 100) has one integrated circuit (22, 122) in a cavity (20, 120) in a package substrate (12, 122) and electrically coupled to one side (50, 150) of the package substrate. A second integrated circuit (32, 132) is mounted on another side of the package device and electrically coupled to that side as well. A third integrated circuit (38, 138) or more may be mounted on the second integrated circuit. Pads (16, 116, 116) useful for testing are present on both sides of the package substrate. The integrated circuits may be tested before final encapsulation to reduce the risk of providing completed packages with non-functional integrated circuits therein.